



Dimensions in inches and (millimeters)

FEATURES

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Metal silicon junction, majority carrier conduction
- Low power loss,high efficiency
 Built-in strain relief,ideal for automated placement
- ◆ High forward surge current capability
- High temperature soldering quarantéed: 250°C/10 seconds at terminals

MECHANICAL DATA

Case: JEDEC DO-214AC molded plastic body Terminals: leads solderable per MIL-STD-750,

Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any Weight: 0.070 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Catalog Number	SYMBOLS	SS22	SS23	SS24	SS25	SS26	SS28	SS210	SS2150	SS2200	UNITS
Maximum repetitive peak reverse voltage	Vrrm	20	30	40	50	60	80	100	150	200	VOLTS
Maximum RMS voltage	VRMS	14	21	28	35	42	56	70	105	140	VOLTS
Maximum DC blocking voltage	VDC	20	30	40	50	60	80	100	150	200	VOLTS
Maximum average forward rectified current at TL(see fig.1)	l(AV)	2.0								Amps	
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	IFSM	50.0								Amps	
Maximum instantaneous forward voltage at 2.0A	VF	0.55 0.70			70	0.85		0.95	Volts		
Maximum DC reverse current Ta=25°C at rated DC blocking voltage Ta=100°C	IR	0.5 0.2 10.0 5.0 2.0							mA		
Typical junction capacitance (NOTE 1)	Сл	220				180				pF	
Typical thermal resistance (NOTE 2)	RθJA	75.0									°C/W
Operating junction temperature range	TJ,	-65 to +125					-65 to +150			°C	
Storage temperature range	Тѕтс	-65 to +150								°C	

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C. 2.P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas



